50V, 100V, 500V, 1KV, 2KV TEMPERATURE COMPENSATING CERAMIC DISC CAPACITOR

Ver: 15

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PRODUCT SPECIFICATION

PRODUCT: CERAMIC DISC CAPACITOR

TYPE: 50V, 100V, 500V, 1KV, 2KV, TEMPERATURE COMPENSATING CAPACITOR

CUSTOMER:

DOC. NO.: POE-D01-00-E-15

Ver.: 15

APPROVED BY CUSTOMER

VENDOR:

☐ WALSIN TECHNOLOGY CORPORATION

566-1, KAO SHI ROAD, YANG-MEI

TAO-YUAN, TAIWAN

☐ PAN OVERSEAS (GUANGZHOU) ELECTRONIC CO.,LTD.

NO.277, HONG MING ROAD, EASTERN SECTION, GUANG ZHOU ECONOMIC AND TECHNOLOGY

DEVELOPMENT ZONE, CHINA

MAKER: PAN OVERSEAS (GUANGZHOU) ELECTRONIC CO.,LTD.

NO.277,HONG MING ROAD,EASTERN SECTION, GUANG ZHOU ECONOMIC AND TECHNOLOGY DEVELOPMENT ZONE,CHINA





Record of change

Date	Version	Description								
2008.6.3	1	1. D08-00-E-14 (befo	$ore) \rightarrow POE-D01-00$	-E-01 (1 st edition)						
2008.8.22	2	1.Revised diameter a	s below:							
		Before	Now	Before	Now					
		CH5000R5X040*	not available	SL500181X060*	SL500181X050*	8-9				
		CH1010R5X040*	not available	SL500241X070*	SL500241X060*	0-7				
		CH501360X050*	CH501360X060*	SL500361X080*	SL500361X070*					
		CH501620X080*	CH501620X060*	SL500391X080*	SL500391X070*					
		CH501680X080*	CH501680X060*	SL101181X060*	SL101181X050*					
		CH501750X080*	CH501750X060*	SL101241X070*	SL101241X060*					
		CH501820X080*	CH501820X070*	SL101361X080*	SL101361X070*					
		CH501101X080*	CH501101X070*	SL101391X080*	SL101391X070*					
		CH102080X060*	CH102080X050*	SL102680X060*	SL102680X050*	6-7				
		CH102100X060*	CH102100X050*	SL102121X100*	SL102121X060*	5				
		CH102120X060*	CH102120X050*	SL102151X100*	SL102151X070*					
		CH102620X080*	CH102620X070*	SL102181X100*	SL102181X070*					
		CH102820X100*	CH102820X080*	SL102201X100*	SL102201X080*					
		C1110202011100	01110202011000	SL102221X100*	SL102221X080*					
		2. Complete lead cod	le	BEIOZZZIATOO	DE10222171000					
			"H" for halogen and l	Pb free , epoxy resin						
2008.12.12	3	1. Complete the 13	th to 17th codes of SAP	P/N.		5-9				
		2. Page layout adjustment.								
			6. Added Marking when the coating resin is Halogen and PB free Epoxy.							
2009.8.19	4		E logo to Walsin & PC ture range change from		25°C - 125°C	13				
					ge from $+85^{\circ}$ C to $+125^{\circ}$ C	15				
		_	erature didn't change)	_	ge 110111 + 03 (10 + 123 (
2010.8.24	5	· •	•		500V 62pF&68pF&75pF.	8				
			(Code of diameter dim			9				
2012/5/10	6	1). Review the size D	Oφ of the item CH/500	V/121&151 from "100)" to be "080";	8				
				00V/820 from "080" to	be "070", CH/1000V/101	8				
		from "100" to be	0,0.							
2012/12/5	7		emp of Allowable Volt			18-19				
2013/5/6	8		l diameter φ from 0.60 ≤6.0mm shall be omit			7,10 9				
						13				
		3. Review the Solderability temperature from $255(+5/-0)^{\circ}$ C to $245\pm5^{\circ}$ C, Solderability time from 2 ± 0.5 s to 5 ± 0.5 s.								
2013/10/18	9	Review the packing	specification			11				
2015/8/31	10	Modify the contents	s of the use of epoxy re	esin for 1KV products		8-9				
			ents of the temperature			5,				
			tion about "Old Part No		1100120\ C DAL CH	6,7				
		3. Delete 300 Pf~ 50V&100V.	-391 pF (Code of d	nameter dimension	is 110&120) for P/N CH	8 8				
2015/9/23										
		of diameter dime	ension is 080) for P/N	CH 500V.		8				
		5. Delete 56 pF &68pF~100pF (Code of diameter dimension is 070) for P/N CH 1KV.								
			oF (Code of diameter ion is 070) for P/N CH		and 24pF~47pF (Code of					
	1		·			6-7				
2016/3/2	12		lable lead code of Lead bient Temp of Allowal		0Vdc to 2kVdc)	17-18				
			ing of internal structure		- · · · · · · · · · · · · · · · · · · ·	19				



Date	Version	Description					
		1. Revised diameter	as below:		9		
		Before	Now				
		SL202181J100*	SL202181J080*				
		SL202201J100*	SL202201J080*				
2016/5/3	13	SL202221J100*	SL202221J080*				
		SL202241J100*	SL202241J080*				
		SL202271J100*	SL202271J080*				
		SL202301J120*	SL202301J110*				
		SL202331J120*	SL202331J110*				
2016/11/3	14	1. Delete "CH" serie	S.		5,8,12~1		
2016/12/21	15	1. Revised the produ	ct diameter for SL 50V	~500V	8		

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1. Part number for SAP system(total eighteen code):

• Temperature characteristic:

SL: +350~-1000ppm/°C

2 Rated voltage (Vdc):

Voltage	50V	100V	500V	1000V	2000V
Code	500	101	501	102	202

3Capacitance(pF):

Capacitors (pF)	47	100	330	470	820
Code	470	101	331	471	821

@Capacitance tolerance : D: $\pm 0.5 pF$ (For6~10pF) \(J: $\pm 5\%$ (For above 10pF)

5 Nominal body diameter dimension:

	Diameter size	4mm	5mm	6mm	7mm	8mm	9mm	10mm	11mm	12mm
Ī	Code	040	050	060	070	080	090	100	110	120

6 Code of lead type: Please refer to Item "2.Mechanical".

• Packing mode and lead's length (identified by 2-figure code)

Taping Code	Description
AN	Ammo / Pitch of component:12.7 mm

Bulk Code	Description
3E	Lead's length L: 3.5mm
04	Lead's length L: 4mm
4E	Lead's length L: 4.5mm
20	Lead's length L: 20mm

8 Length tolerance

Code	Description
A	±0.5 mm(Only for short kink lead code)
В	±1.0 mm
С	Min.
D	Taping special purpose

9Pitch

Code	Description	Code	Description
5	5.0±0.8mm (For Bulk)	7	7.5 ±1mm
5	5.0+0.8mm-0.2mm (For Taping)	0	10.0 ±1mm
2	2.5 ±0.8 mm		

Coating code

outing code				
Code Description				
P	Phenolic resin -Pb free			
A	Halogen free and Pb free, phenolic resin			
В	Epoxy Resin, Pb free			
Н	Halogen free and Pb free, epoxy resin			

2. Mechanical:

Available lead code: (unit: mm)

Available lea		. 111111 <i>)</i>				
Lead type	SAP P/N (13-17) digits	Pitch (F)	Lead length (L)	Available rated voltage	Packing	Lead configuration
	B20C2	2.5 ± 0.8	20 MIN.	50V&100V		D max. T max.
	B20C5	5.0 ± 0.8	20 MIN.	20,00100,		
	B20C6	6.4 ± 1.0	20 MIN.	-	Bulk	
Lead style: B	B20C0	10 ± 1.0	20 MIN.	50V&100V, 500V,		()
Straight long	B20C7	7.5 ± 1.0	20 MIN.	1KV,2KV		
lead	BAND5	5.0 +0.8 -0.2	Taping Spec. (Ref.		Tap. Ammo	* T F - 1
	BAND2	2.5 ± 0.8	to page.10)	50V&100V	rup. 7 mmo	Ø d
	L05B2	2.5 ± 0.8	5.0 ± 1.0			D max. T max.
	L05B5	5.0 ± 0.8	5.0 ± 1.0			
	L05B0 L05B6	10 ± 1.0	5.0 ± 1.0 5.0 ± 1.0			/ \
Lead style: L	L05B7	6.4 ± 1.0 7.5 ± 1.0	5.0 ± 1.0 5.0 ± 1.0		5 "	()
Straight short	L4EB5	5.0 ± 0.8	4.5 ± 1.0	50V&100V, 500V, 1KV, 2KV	Bulk	
lead	L4EB7	7.5 ± 1.0	4.5 ± 1.0	1KV, 2KV		*
	L4EB0	10 ± 1.0	4.5 ± 1.0			ø d L
	H3EA5	5.0 ± 0.8	3.5 ± 0.5			, , , , , , , , , , , , , , , , , , , ,
	H04A5	5.0 ± 0.8	4.0 ± 0.5	•		
	H4EB5	5.0 ± 0.8	4.5 ± 1.0	50V&100V, 500V,	Bulk	
	H05B5	5.0 ± 0.8	5.0 ±1.0	1KV		_
	H20C5	5.0 ± 0.8	20 MIN.			D max. T max.
Lead style: H	HAND5	5.0 +0.8 -0.2	Taping SPEC. (Ref. to page.10)		Tap. Ammo	
x · 1 1 · 1	H05B7 H05B0	7.5 ± 1.0 10 ± 1.0	5.0 ±1.0			\ \
Inside kink	H20C0	10 ± 1.0 10 ± 1.0	5.0 ±1.0 20 MIN.	-		xi-
lead	H04A7	7.5 ± 1.0	4.0 ± 0.5	-		
	H04A0	10 ± 1.0	4.0 ± 0.5	50V&100V, 500V,	Bulk	
	H3EA7	7.5 ± 1.0	3.5 ± 0.5	1KV,2KV		
	H3EA0	10 ± 1.0	3.5 ± 0.5			
	H4EB7	7.5 ± 1.0	4.5 ± 1.0			
	H4EB0	10 ± 1.0	4.5 ± 1.0			
	X3EA5	5.0±0.8				
	X3EA7	7.5±1.0	3.5 ± 0.5			D max. T max.
	X3EA0	10±1.0				
Lead style: X	X04A5	5.0±0.8		50110 10011 50011		()
Outside kink	X04A7	7.5±1.0	4.0 ± 0.5	50V&100V, 500V, 1KV, 2KV	Bulk	.,\ \ \ \
lead	X04A0	10±1.0		1KV, 2KV		S. S
	X05B5	5.0±0.8]		
	X05B7	7.5±1.0	5.0 ± 1.0			
	X05B0	10±1.0	1			
	D04A5	5.0±1.0				•
		1	40.05			D max.
T 1	D04A7	7.5±1.0	4.0 ± 0.5			
Lead style : D	D04A0	10±1.0			Bulk	()
Vertical kink	D3EA5	5.0±0.8		50V&100V, 500V,		\ \ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\
short lead	D3EA7	7.5±1.0	3.5 ± 0.5	1KV, 2KV		4.0mmax
	D3EA0	10±1.0				F -
	DAND5	5.0 ^{+0.8} -0.2	Taping SPEC. (Ref. to page.10)		Tap. Ammo	Ø d→
		1	(1.01. to page.10)	1		



Lead type	SAP P/N (13-17) digits	Lead length (L)	Available rated voltage	Packing	Lead configu	ıration
	M05B5				D max.	T max.
	M05B7	5.0 ± 1.0	50V&100V, 500V, 1KV, 2KV			
	M05B0					
Lead style: M	M04B5				()	
Double outside	M04B7			Bulk	ki l	y y
kink lead	M04B0	4.0 ± 1.0			F _Ø d ₋	

- \times Lead diameter φ = 0.55 +/-0.05mm
- \divideontimes Phenolic resin coating for 50V/500V/1KV product; Epoxy resin coating for 1KV or 2KV product.
- **※ e** (Coating **extension** on leads):

For straight lead style: 1.5mmMax when the rated voltage is 50Vdc & 100Vdc;

2.0mmMax when the rated voltage is 500Vdc and 1KVdc;

3.0mmMax when the rated voltage is 2KVdc.

For kink lead style: not exceed the kink.

%When Dφ≥11mm, only for bulk, but Dφ≤10mm can do Bulk or Taping.



3. Capacitance value vs. rated voltage, product diameter:

T.C										S	\mathbf{L}									
Rate voltage	50V/100V							500V				1 F	ίV			2H	ζV			
Dφ	040	050	060	070	080	090	100	050	060	070	080	100	050	060	070	080	060	070	080	110
D max. (mm)	5.0	6.0	7.0	8.0	9.0	10.0	11.0	6.0	7.0	8.0	9.0	11.0	6.0	7.0	8.0	9.0	7.5	8.5	9.5	12.5
T max. (mm)	3.5	3.5	3.5	3.5	3.5	3.5	3.5	4.0	4.0	4.0	4.0	4.0	4.5	4.5	4.5	4.5	4.5	4.5	4.5	4.5
2																				
3 4																				
5																				
6																				
7																				
8	080							080												
10	100							100					100							
12	120							120					120				150			
15 18	150 180							150 180					150 180				150 180			
20	200							200					200				200			
22	220							220					220				220			
24	240							240					240				240			
27	270							270					270				270			
30	300							300					300				300			
33	330							330					330				330			
36	360							360					360				360			
39 47	390							390 470					390				390 470			
51	470 510							510					470 510				510			
56	560							560					560				560			
68	680							680					680				680			
75	750							750					000	750			750			
82	820							820						820			820			
100	101							101						101				101		
120		121							121					121					121	
150		151							151						151				151	
180		181	201							181					181	201			181	
200 220			201							201 221						201			201 221	
240			241							221	241					221			241	
270			241	271							271								271	
300				301							301									301
330				331							331									331
360				361								361								
390				391								391								
470					471	501														
500 510						501 511														
560						561														
680						301	681													
750							751													
820							821													
PACKING			TAP	NG or B	ULK				TAP	ING or B	ULK			TAPING			TAP	ING or E	ULK	BULK
COATING						Phenol	ic resin						Pheno	lic resin	or Epoxy	Resin		Epoxy	Resin	

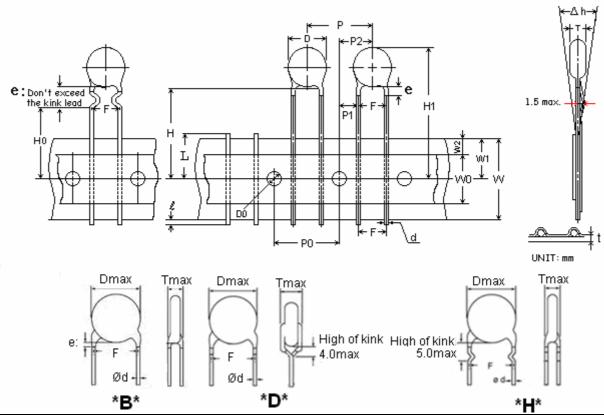
4. Marking:

i. Marking:					
		SL			
	a ((1)			
Marking	(3)	4/J (4)			
Remarks	3 ((5) (5)			
(1). Temp. char.	SL: No markir	ng.			
(2). Rated capacitance	Identified by 3-	Figure Code. Ex. 47pF→"47",470pF→"471"			
	50V&100V	Marked with code "" under the rated capacitance.			
(3). Rated voltage	500V	No any marking under the rated capacitance.			
	1000V&2000V	Marked with code: 1000V→"1KV", 2000V→"2KV"			
(4). Capacitance tolerance	C: ±0.25pF (For below 5pF) \ D: ±0.5pF (For6~10pF) \ J: ±5% (For above 10pF)				
(5). Manufacturer's identification	Shall be marked	d as "♥", but DΦ≤060 shall be omitted.			
(6). Halogen and Pb free	There is a "" Pb free Epoxy.	marking under the code "V" when the coating resin is Halogen and			

5. Taping specifications:

* Lead spacing: **F**=5.0 ^{+0.8}_{-0.2} (**mm**)

• 12.7mm pitch/lead spacing 5.0mm taping Lead code: *BAND5 & *DAND5 & *HAND5

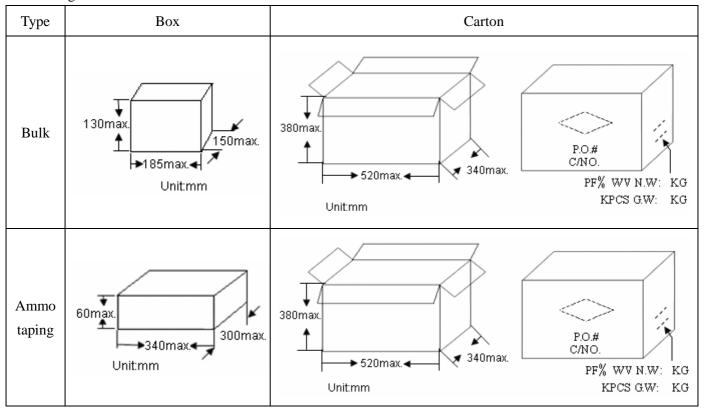


Item			Spec	cification	Remarks		
			Value	Tolerance	Kemarks		
Body diameter		D	*	max.	See Section"3. Capacitance value vs. rated		
Body thickness		T	*	max.	voltage, product diameter".		
Lead-wire diameter		d	0.55	±0.05			
Pitch of component		P	12.7	±1.0			
Feed hole pitch		P0	12.7	±0.3	Cumulative pitch erroe:1.0mm/20 pitch		
Feed hole center to lead		P1	3.85	±0.7	To be measured at bottom of clinch		
Hole center to component center		P2	6.35	±1.3			
Lead-to-lead distance			5.0	+0.8,-0.2			
Component alignment, F-R			0	±2.0			
Tape width		W	18.0	+1.0,-0.5			
Hole-down tape width		W0	8.0	min.			
Hole position		W1	9.0	+0.75,-0.5			
Hole-down tape position		W2	3.0	max.			
Height of component form tape	For straight lead type	Н	20.0	+1.0 -0.5			
center	For kinked lead type	H0	16.0	±0.5			
Component height			32.25	max.			
Lead-wire protrusion			2.0	max.	Or the end of lead wire may be inside the tape.		
Food hole diameter			4.0	±0.2			
Total tape thickness			0.7	±0.2	Ground paper:0.5±0.1mm		
Length of sniped lead			11.0	max.			
Coating rundown on leads		e	Please refer to page 6 "e(Coating extension on leads)".				



6. Packing Baggage:

6.1 Packing size:



6.2 Packing quantity:

Packing Type	The	e code of 14th to15th in SAP P/N	MPQ (MPQ (Kpcs/Box)		
Tanina		AN	2		Phenolic resin	
Taping		AN	1.5		Epoxy resin	
Packing Type	Lead length	ead length Size code of 10th to 12th in SAP P/N MPQ (Kpcs/Bag)		Kpcs/Box	Remark	
		040~070	1	3	Phenolic resin	
	Long lead	080~100	1	2	Phenolic resin	
	(L≧16mm)	050~100	1	2	Epoxy resin	
D11-		110~120	0.5	1.5		
Bulk		040~060	1	6		
	Short lead	070~080	1	4		
	(L<16mm)	090~100	1	3		
		110~120	1	2		

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7. Specification and test method:

- 7.1 SCOPE: THIS SPECIFICATION APPLIES TO TEMPERATURE COMPENSATING CERAMIC DISC CAPACITOR.
- 7.2 TEST CONDITIONS:

UNLESS OTHERWISE SPECIFIED, ALL TESTS SHALL BE OPERATED AT THE STANDARD TEST CONDITIONS OF TEMPERATURE 5°C TO 35°C AND RELATIVE HUMIDITY 45% TO 85%. WHEN FAILS A TEST, RETEST BE OPERATED AT THE CONDITIONS OF TEMPERATURE 25°C \pm 2°C, RELATIVE HUMIDITY OF 60% TO 70% AND BAROMETRIC PRESSURE 860 TO 1060 MBAR.

7.3 HANDLE PROCEDURE: TO AVOID UNEXPECT TESTING RESULTS FROM OCCURRING, THE TESTED CAPACITOR MUST BE KEPT AT ROOM TEMPERATURE FOR AT LEAST 30 MINUTES AND COMPLETELY DISCHARGED.

7.4 TEST ITEMS:

	T						
ITEM	POST-TEST	REQUIREMENTS	TESTING PROCEDURE				
APPEARANCE STRUCTURE SIZE	NO ABNOR	MALITIES	AS SECTION 3.				
MARKING			AS STATED IN SECTION 4				
	BETWEEN NO ABNOR	TERMINALS: MALITIES	A. BELOW 1KV: 300% RATED VOLTAGE WITH 50mA MAX. CHARGING CURRENT FOR 1~5 SEC. B. 1KV & ABOVE: 200% RATED VOLTAGE WITH 50mA MAX. CHARGING CURRENT FOR 1~5 SEC.				
WITHSTAND VOLTAGE	BETWEEN ENCLOSUR		SMALL METALLIC BALLS WITH 1mm DIAMETERS SHALL BE PUT ON A VESSEL AND THE TEST CAPACITOR SHALL BE SUBMERGED EXCEPT 2mm FROM THE TOP OF ITS COMPONENT BODY. THE TEST VOLTAGE SHALL BE APPLIED BETWEEN THE SHORT-CIRCUITED TERMINALS AND THE METALLIC BALLS. (APPLY 1.3KV DC OF RATED VOLTAGE BETWEEN TERMINALS AND ENCLOSURE FOR 1~5 SEC)				
INSULATION RESISTANCE	10000 ΜΩ Ν		INSULATION RESISTANCE SHALL BE MEASURED AT 60±5 SECONDS AFTER APPLIED VOLTAGE (RATED) RATED VOLTAGE: 50V=50V, 100V=100V, 500V & ABOVE=500V				
CAPACITANCE	TOLERANCE : C : ±0.25PF D : ±0.50PF J : ±5% K : ±10%		TESTING FREQUENCY : 1 MHZ ± 20% TESTING VOLTAGE : 1.0 VRMS				
OPERATING TEMPERATURE RANGE	-25°C ∼ -	+125℃					
Q FACTOR	30 PF & ABOVE BELOW 30PF	$Q \ge 1000$ $Q \ge 400+20 \times C$	- AS ABOVE STIPULATION OF CAPACITANCE				

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ITEM	POST-TEST REQUIREMENTS		TEST	ING	PROC	CEDURI				
		ACCORDING TO STEP 1 TO 5 IN ORDER, MEASURED CAPACITANCE WHEN TEMPERATURE REACH BALANCE AND TEMPERATURE COEFFICIENT SHALL BE CALCULATED ON THE FOLLOWING FORMULA: PPM/°C =(C2-C1)×10E6/C1(T2-T1)								
	TEMPERATURE COEFFICIENT : SL :+350~-1000 ppm/°C	Step	1	2	3	4	5]		
	FOR (+20°C ~+85°C)	Temp. (°C)	20±2	-25±3	20±2	85±2	20±2			
TEMPERATURE CHARACTERISTIC		NOTE : C1 = C2 = CAPAC: T1 = TEMPE: T2 = TEMPE:	ITANCE RATURI	E AS STE E AS STE	P 2 OR EP 3	4				
	CAPACITANCE TOLERANCE : WITHIN ±0.2% OR ±0.05PF, WHICHEVER IS LARGE	ACCORDING TO ABOVE STEP 1,3 & 5, CAPACITANCE TOLERANCE SHALL BE CALCULATED ON THE FOLLOWING FORMULA: △C%=(G - S)/C1 NOTE: G = GREATEST CAPACITANCE AS TESTING RESULT OF STEP 1,3 & 5 S = LEAST CAPACITANCE AS TESTING RESULT OF STEP 1,3 & 5 C1 = CAPACITANCE AS STEP 3								
TERMINAL	TENSIBLE STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 M/M. LOADING WEIGHT 0.5 KGS, FOR 10±1 SECONDS. WIRE DIA.0.6 M/M. LOADING WEIGHT 1.0 KGS, FOR 10±1 SECONDS.								
STRENGTH	BENDING STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 mm, LOADING WEIGHT 0.25 KGS. WIRE DIA.0.6 mm, LOADING WEIGHT 0.5 KGS. (BENDING BACK AND FORTH 90 DEGREE TWICE)								
	APPEARANCE : NO ABNORMALITIES	LEAD WIRE OR TERMINALS SHALL BE IMMERSED UP TO 2.0 M/M FORM BODY. (A) BODY DIA. ≤ 5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE: 260(+5/-0)°C FOR 3.0±0.5								
SOLDERING	CAP.CHANGE: WITHIN ±2.5% OR ±0.25PF, WHICHEVER IS LARGE.	SECONDS. (B) BODY DIA. > 5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE 260(+5/-0)°C FOR 5~10 SECONDS.								
HEAT RESISTANCE	WITHSTAND VOLTAGE: (BETWEEN TERMINALS) NO ABNORMALITIES	THEN LEAVE AT STANDARD TEST CONDITIONS FOR 1~2 HOURS, THEN MEASURED. **WHEN SOLDERING CAPACITOR WITH A SOLDERING IRON, IT SHOULD BE PERFORMED IN FOLLOWING								
		CONDITIONS. TEMPERATURE OF IRON-TIP: 350~400 °C SOLDERING IRON WATTAGE: 50W MAX.								
SOLDERABILITY	SOLDERING TIME : 3.5 SEC. MAX. LEAD WIRE SHALL BE SOLDERED OVER 75% OF THE CIRCUMFERENTIAL DIRECTION. SOLDERING TIME : 3.5 SEC. MAX. TO COMPLY WITH JIS-C-5102 8.4 SOLDER TEMPERATURE245±5°C AND DIPPING TIME 5 SECONDS FLUX : WEIGHT RATIO OF ROSIN 2			± 0.5						

50V, 100V, 500V, 1KV, 2KV TEMPERATURE COMPENSATING CERAMIC DISC CAPACITOR | Ver: 15 | Page: 13 of 19

ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE
HUMIDITY CHARACTERISTIC	APPEARANCE: NO ABNORMALITIES CAP. CHANGE: SL: WITHIN $\pm 5\%$ OR ± 0.5 PF, WHICHEVER IS LARGE Q FACTOR: SL: LESS THAN 10 PF ==> Q $\geq 200 + 10 \times C$ MORE THAN 10 PF AND LESS THAN 30 PF => Q $\geq 275 + 5 \times C / 2$ MORE THAN 30 PF => Q ≥ 350 INSULATION RESISTANCE: 1000 M Ω MIN.	CAPACITORS SHALL BE SUBJECTED TO A RELATIVE HUMIDITY OF 90 \sim 95% AT 40 \pm 2°C FOR 500(\pm 24/-0) HOURS, THEN DRIED FOR 1 \leftarrow 2 HOURS AND MEASURED.
HUMIDITY LOADING	APPEARANCE: NO ABNORMALITIES CAP.CHANGE: SL: WITHIN $\pm 7.5\%$ OR ± 0.75 PF, WHICHEVER IS LARGE Q FACTOR: SL: LESS THAN 30 PF => Q $\geq 100 + 10 \times C / 3$ MORE THAN 30 PF => Q ≥ 200 INSULATION RESISTANCE: 500 M Ω MIN.	CAPACITORS SHALL BE SUBJECTED TO A RELATIVE HUMIDITY OF 90 \sim 95% AT 40±2°C FOR 500(+24/-0) HOURS WITH RATED VOLTAGE APPLIED (LESS THAN 50mA), THAN DRIED FOR 1 \sim 2 HOURS AND MEASURED.
HIGH TEMPERATURE LOADING	APPEARANCE: NO ABNORMALITIES CAP. CHANGE: SL: WITHIN ±3% OR ±0.3PF, WHICHEVER IS LARGE Q FACTOR: SL: LESS THAN 10PF => Q \geq 200 + 10 × C MORE THAN 10PF & LESS THAN 30PF => Q \geq 275 + 5 × C / 2 MORE THAN 30PF => Q \geq 350 INSULATION RESISTANCE: 1000M Ω MIN.	CAPACITORS SHALL BE SUBJECTED TO A TEST OF: (A) BELOW 1KV: 200% RATED VOLTAGE WITH 50mA MAX. (B) 1KV & ABOVE: 150% RATED VOLTAGE WITH 50mA MAX. FOR 1000(+48/-0) HOURS AT 125°C ± 2°C (FOR CH & SL) AND THEN DRIED FOR 1~2 HOURS AND MEASURED.



ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE
	APPEARANCE : NO ABNORMALITIES	CAPACITORS SHALL BE SUBJECTED TO: $-25\pm3^{\circ}\mathbb{C}(30\pm3\min) \rightarrow 25^{\circ}\mathbb{C}(3\min) \rightarrow 125\pm3^{\circ}\mathbb{C}(30\pm3\min) \rightarrow 25^{\circ}\mathbb{C}(30\pm3\min) \rightarrow 25^{\circ}\mathbb{C}(30\pm3\min) \rightarrow 35^{\circ}\mathbb{C}(30\pm3\min) \rightarrow 35^{\circ}$
	CAP. CHANGE :	25°C (3min) FOR 5 CYCLE.
TEMPERATURE	WITHIN ±5% OR ±0.5PF, WHICHEVER IS LARGE	
CYCLING	D.F. $C < 30pF : Q \ge 275 + (5/2)C$	
	$C \ge 30 \text{pF} : Q \ge 350$	
	INSULATION RESISTANCE : $1000 \text{ M}\Omega$ MIN.	



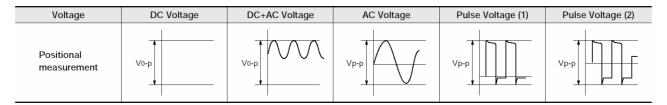
8. Cautions & notices:

8.1. Caution (Rating)

I. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.



II. Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high frequency current, pulse current or similar current, it may self-generate heat due to dielectric loss. The frequency of the applied sine wave voltage should be less than 100kHz. The applied voltage load (*) should be such that the capacitor's self-generated heat is within 20°C at an atmosphere temperature of 25°C. When measuring, use a thermocouple of small thermal capacity-K of \emptyset 0.1mm in conditions where the capacitor is not affected by radiant heat from other components or surrounding ambient fluctuations.

Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

III. Fail-Safe

When capacitor is broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

8.2. Caution (Storage and operating condition)

I. Operating and storage environment

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed –10 to 40 degrees centigrade and 15 to 85 % for 6 months maximum and use within the period after receiving the capacitors.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.



8.3. Caution (Soldering and Mounting)

I. Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

II. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor.

Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element. When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage: 50W max.

Soldering time: 3.5 sec. max.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

8.4. Caution (Handling)

Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRDUCT IS USED.

8.5. Notice

8.5.1. Notice (Soldering and Mounting)

Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

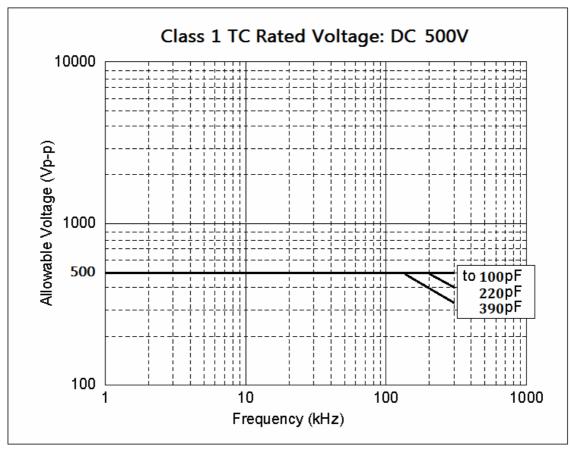
Rinse bath capacity: Output of 20 watts per liter or less.

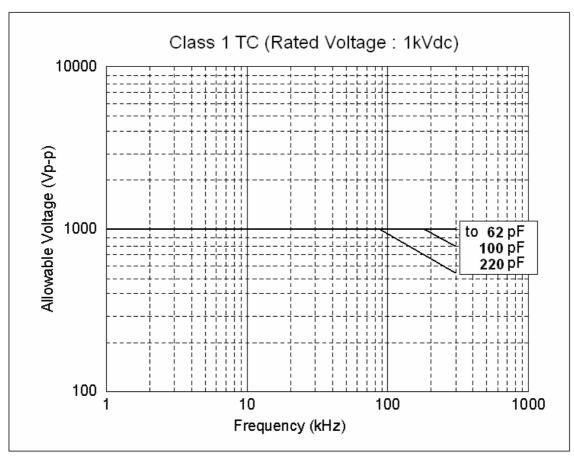
Rinsing time: 5 min. maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

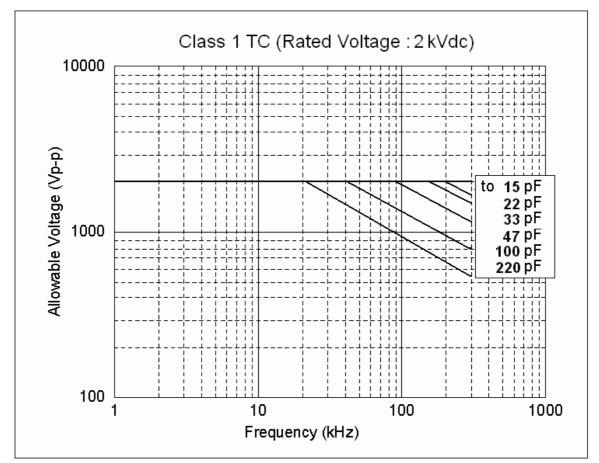
8.6. Ambient Temp of Allowable Voltage Graph (500Vdc to 2kVdc)

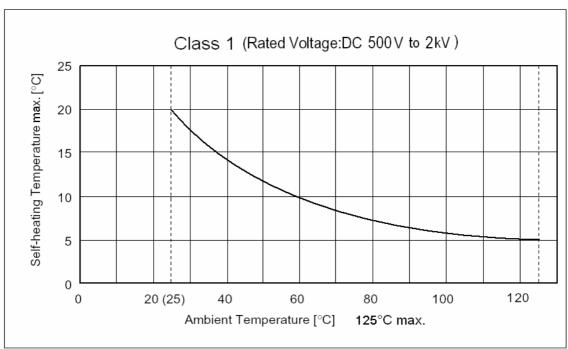




50V, 100V, 500V, 1KV, 2KV TEMPERATURE COMPENSATING CERAMIC DISC CAPACITOR

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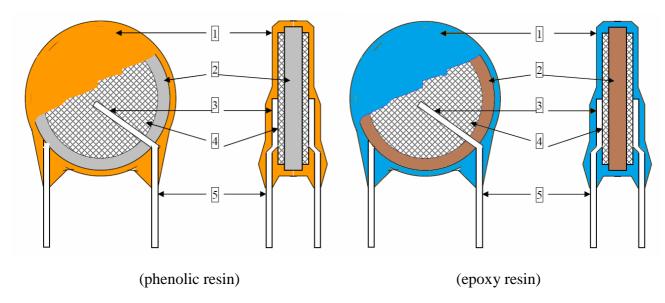




The ambient temperature and the surface temperature of capacitor must be 125°C or lower. (Including self-heating.)



9. Drawing of internal structure and material list:



NO.	部位	材質	構成部份	供應商
NO.	Part name	Material	Component	Vendor
1	Inculation Coating	Phenolic resin	Phenolic resin, Filler, Pigment	Namics
1	Insulation Coating	Epoxy resin	Epoxy resin, SiO2, TiO2	Kai Hua
				Hua Xing
2	2 Dielectric Element	Dielectric Element Ceramic	BaTiO3	Wang Feng
				Fenghua
3	Solder	Tin-silver	Sn97.5-Ag2.5	Huajun
3	Solder	TIII-SIIVEI	51197.3-Ag2.3	Haili
4	Electrodes	Λ ~	Silver,Glass frit	Daejoo
4	Electiodes	Ag	Silver, Glass IIII	Xinguang
5	Leads wire	Tinned copper	Substrate metal:Fe&Cu	Hengtai
3	Leaus wife	clad steel wire	Surface plating:Sn 100%	Wuhu Taililai

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NCD331K1KVY5FF 440LT68AP-R CK60AX471M AOL-1502-02 DEF2CLH040CN3A DEF2CLH080DA3B 0811-040-X7R0-102K
8903D0 90410-10 YV101103Z060HAND5P SL102101J060BAND5P ZU501103M090B20C6P ZU102103M100X05B0P
YP102271K050B20C6P YP102391K050BAND5P YP501101K040BAND5P ZU102103M100BAND5H YP102681K060B20C6P
YP501121K040B20C6P SL102181J070HAND5P YP501471K040B20C6P SL102151J070HAND5P YP501102K050HAND5P
ZU501102M050B20C6P YP501472K100B20C6P ZU102103M100B20C0P YV500223Z080HAND5P CC1H220KA1EDCH4B1100
SL500330J040B20C2P SL501510J050B20C6P SL102221J080HAND5P YP500103M100HAND5P YP102101K050B20C5B
YP500472K070HAND5P SL102101J060HAND5H YP500102K040HAND5P YP10222ZK080D20C5B